

Surface Mount Fuse, PTC, 2018 footprint, 5.1 x 4.6 mm, 60 VDC



60.0VDC · 0.55A



**Description**

- Directly solderable on printed circuit boards

**Standards**

- UL 1434  
- CSA C22.2 no. 0, TIL no. CA-3A

**Approvals**

- UL File Number: E172175  
- CSA File Number: 702083

**Applications**

- Power Over Ethernet (IEEE 802.3 af) port protection  
- Automotive electronic control module protection  
- Telecom equipment low voltage protection

**References**

[Packaging Details](#)

**Weblinks**

[pdf](#), [html](#), [General Product Information](#), [Approvals](#), [RoHS](#), [CHINA-RoHS](#), [e-Store](#), [SCHURTER-Stock-Check](#), [Distributor-Stock-Check](#)

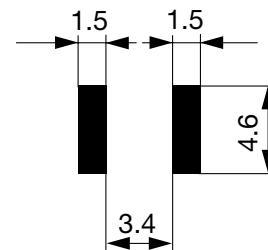
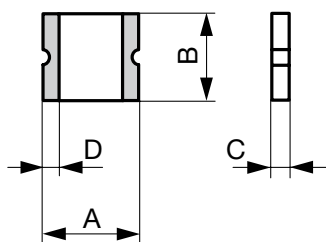
**Technical Data**

|                           |  |
|---------------------------|--|
| V max                     | 60.0VDC                                |
| I max                     | 10A                                    |
| I hold                    | 0.55A                                  |
| Mounting                  | PCB,SMT                                |
| Allowable Operation Temp. | -40 °C to 85 °C                        |
| Material: Terminals       | Electroless Nickel under Immerion Gold |
| Weight                    | 0.03 g                                 |
| Storage Conditions        | 0 °C to 40 °C, max. 70% r.h.           |
| Product Marking           | I hold, Data Code                      |

|                              |  |
|------------------------------|--|
| Soldering Methods            | Reflow   |
| Solderability                | 245 °C / 3 sec   |
| Resistance to Soldering Heat | 260 °C / 10 sec  |
| Passing Aging                | +85 °C, 1000 Hours -> +/- 5% Typical Resistance Change           |
| Humidity Aging               | +85 °C, 85% r.h., 1000 Hours -> +/- 5% Typical Resistance Change |
| Thermal Shock                | +85 °C to -40 °C, 20 Times -> +/- 10% Typical Resistance Change  |
| Vibration                    | MIL-STD-883C, Method 2007.1, Test Condition A                    |
| Resistance to Solvents       | MIL-STD-202, Methode 215   |

**Dimensions**

5.1 mm



Soldering pads

**Dimensions**

| A min [mm] | A max [mm] | B min [mm] | Insert depth | C min [mm] | C max [mm] | D min [mm] | Order Number |
|------------|------------|------------|--------------|------------|------------|------------|--------------|
| 4.72       | 5.44       | 4.22       | 4.93         | 0.79       | 1.09       | 0.3        | PDFD.050.2   |

### Thermal Derating Chart Ihold [A]

| Order Number | -40 °C | -20 °C | 0 °C | 23 °C | 40 °C | 50 °C | 60 °C | 70 °C | 85 °C | Order Number |
|--------------|--------|--------|------|-------|-------|-------|-------|-------|-------|--------------|
| PFDF.050.2   | 0.86   | 0.77   | 0.7  | 0.55  | 0.48  | 0.43  | 0.38  | 0.36  | 0.26  | PFDF.050.2   |

### Electrical Characteristics at 23 °C

| V max [VDC] | I max [A] | I hold [A] | I trip [A] | R initial min [Ω] | R 1hour max [Ω] | Max Time to trip [A] | Max Time to Trip [s] | Tripped Power Dissipation [W] | Order Number |
|-------------|-----------|------------|------------|-------------------|-----------------|----------------------|----------------------|-------------------------------|--------------|
| 60.0        | 10        | 0.55       | 1.2        | 0.2               | 1               | 2.5                  | 3                    | 1.00                          | PFDF.050.2   |

**Packaging Unit** Blister Tape 36 cm Reel (6000 pcs.)

### Time-Current-Curves

